

## **REMARKS**

Election of claims 12-20 is affirmed for prosecution under this application. Claims 1-11 are deleted.

In the Office Action, examiner objected to the drawings for failing to show every feature of the invention specified in the claims. In response to this objection, drawing FIG.1A is added to show a contact in a bore of the base plate and soldered to a pad on the circuit board.

Claims 12-20 were rejected under 35 U.S.C. sec. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claims 12-20 were rejected under 35 U.S.C. 103(a) as being unpatentable over Bright et al., and Claims 12, 14-17 and 20 were rejected under 35 U.S.C. 103(a) as being unpatentable over Kozel.

In response to these rejections, Claims 12-16 and 19-20 have been amended to more particularly point out and distinctly claim the subject matter which applicant regards as the invention. Claims 17 and 18 remain unchanged. Claim 21 is newly added. The rejections under 35 U.S.C.103(a) are traversed below.

The inventive feature in the instant invention is a base plate of a connector having a regular arrangement of the molecules of the dielectric material constituting the base plate, together with the shape, size and pattern of holes in the base plate, aside from the contact receiving bores in the base plate.

The holes in the base plate are unique from the bores in the base plate and have an entirely different purpose from the bores. The purpose of the bores is only to provide a mounting location for the

contacts in the base plate, a location for insertion of pins of the electronic device, and a location for mating and unmating of the pins with the contacts. The holes in the base plate, on the other hand, provide an entirely different function, which is to configure the material of the base plate on a molecular level so that the molecules of the base plate have a regular arrangement, resulting in the coefficient of thermal expansion being more nearly the same along a lateral dimension and along a longitudinal dimension of the base plate. The holes in the base plate contain no contacts and perform their configuration function by directing the flow of plasticized dielectric material in its fluid state during injection molding of the base plate. The holes in the base plate may also have the further effect of, in and of themselves, altering the coefficients of thermal expansion of the material by their size and placement in the finished base plate. These coefficients of thermal expansion of the base plate are also more nearly equal to the coefficient of thermal expansion of a circuit board on which the connector can be mounted. This is a new and useful configuration of the base plate since changes in temperature in the base plate and the circuit board will cause smaller differences in expansion between the two and thus smaller stresses in the soldered joints between each individual contact and each conductive pad on the circuit board. This decrease in stress is significant because it will yield more reliable connections between the contacts and the circuit board, and less incidence of failures of these soldered connections.

The prior art cited by the examiner fails to suggest or to mention either such an improvement at the molecular level, or any arrangement by which such an improvement can be effected. Indeed, the cited prior art fails to mention even coefficients of thermal expansion, showing a complete lack of concern for the problem addressed and overcome by the present invention. Therefore, said prior art can not render the inventive feature of the instant invention obvious.

Applicant therefore respectfully requests that examiner allow the claims 12-21 presently pending in the application.

In view of the above claim amendments, the subject application is believed to be in a condition for allowance and an action to such effect is earnestly solicited.

Respectfully submitted,  
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